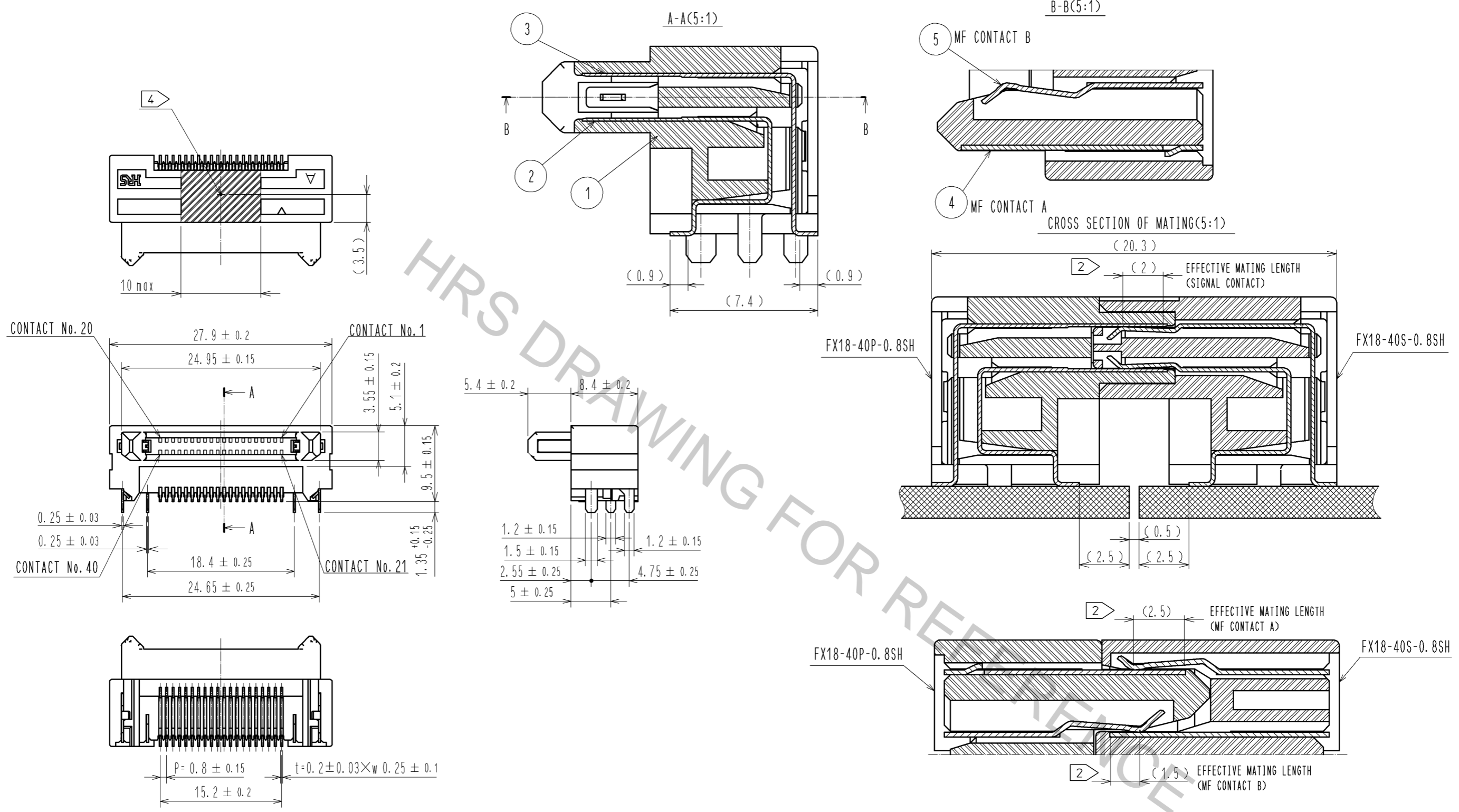


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- NOTE 1 LEAD CO-PLANARITY IS 0.1mm MAX.  
 2 CONTACTS ARE 3 STEPS SEQUENTIAL. (MF CONTACT A->SIGNAL CONTACT->MF CONTACT B) WHEN USING THIS SEQUENTIAL STRUCTURE, PLEASE AVOID ANGLED INSERTION.  
 3 MF CONTACT A AND MF CONTACT B CAN BE USED AS POWER SUPPLY CONTACT. (3A/PIN MAX)  
 4 IT SHOWS CONNECTOR'S CENTRE OF GRAVITY AND VACUUM PICKUP AREA.  
 5 THIS IS PACKAGED IN TRAY. (70pcs/TRAY)  
 6 BLEMISH AND HIT MARK CAN BE OCCURED THROUGH OUT THE MANUFACTURING PROCESS WHICH DOESN' T AFFECT QUALITY LEVEL.  
 7 THE DIMENSIONS IN PARENTHESES ARE FOR REFERENCES.

NO.	MATERIAL	FINISH	REMARKS	NO.	MATERIAL	FINISH	REMARKS
3	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:GOLD 0.03µm UNDER PLATING:NICKEL 1.3µm		6	POLYSTYRENE		
2	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:GOLD 0.03µm UNDER PLATING:NICKEL 1.3µm		5	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:TIN-PLATING 1µm UNDER PLATING:NICKEL 1.3µm	
1	POLYAMIDE	BLACK UL94V-0		4	PHOSPHOR BRONZE	CONTACT AREA:GOLD 0.1µm LEAD AREA:TIN-PLATING 1µm UNDER PLATING:NICKEL 1.3µm	

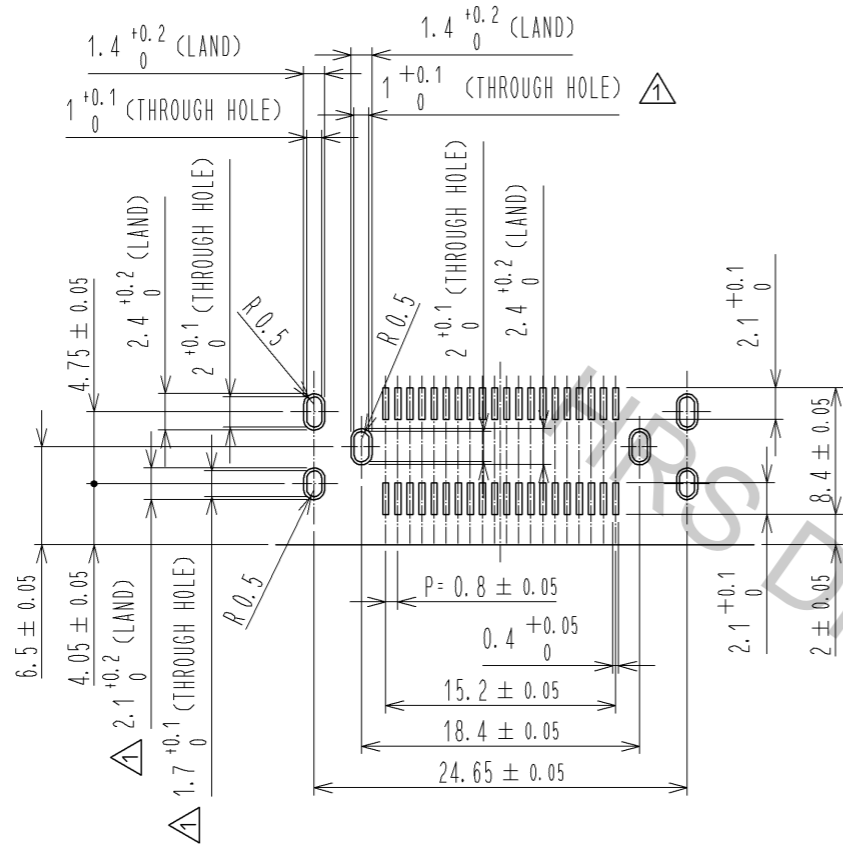
  

UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	2:1	4	DIS-F-005578	TH. SANO	KI. HIROKAWA	11.07.21

APPROVED	CHECED	DESIGNED	DRAWN	DRAWING NO.	PART NO.	CODE NO.
HS. OKAWA	KI. HIROKAWA	TH. SANO	TH. SANO	EDC3-159074-00	FX18-40P-0.8SH	CL579-0002-5-00
09.10.09	09.10.09	09.10.09	09.10.09			

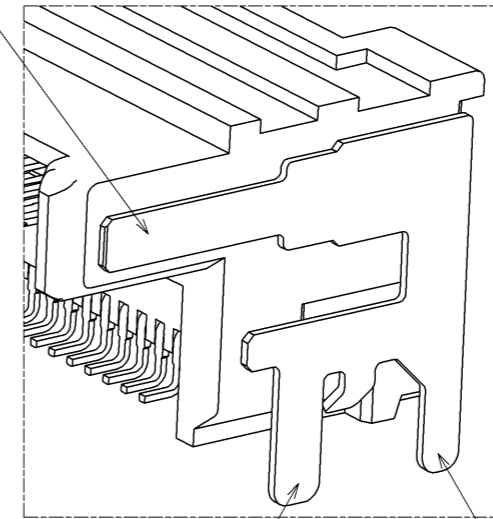
RECOMMENDED LAND PATTERN DIMENSION OF PCB(2:1)  
 (PCB THICKNESS: t=1.6mm, METAL MASK THICKNESS: t=0.12mm)



5 DRAWING FOR PACKING(1:2)

8 CONFIGURATION OF MF CONTACT A

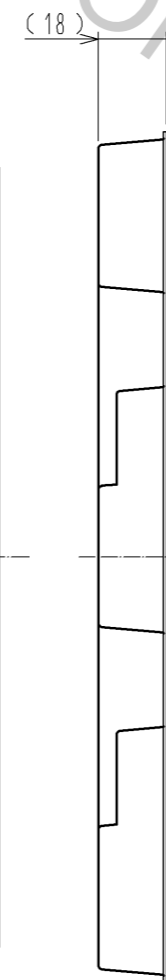
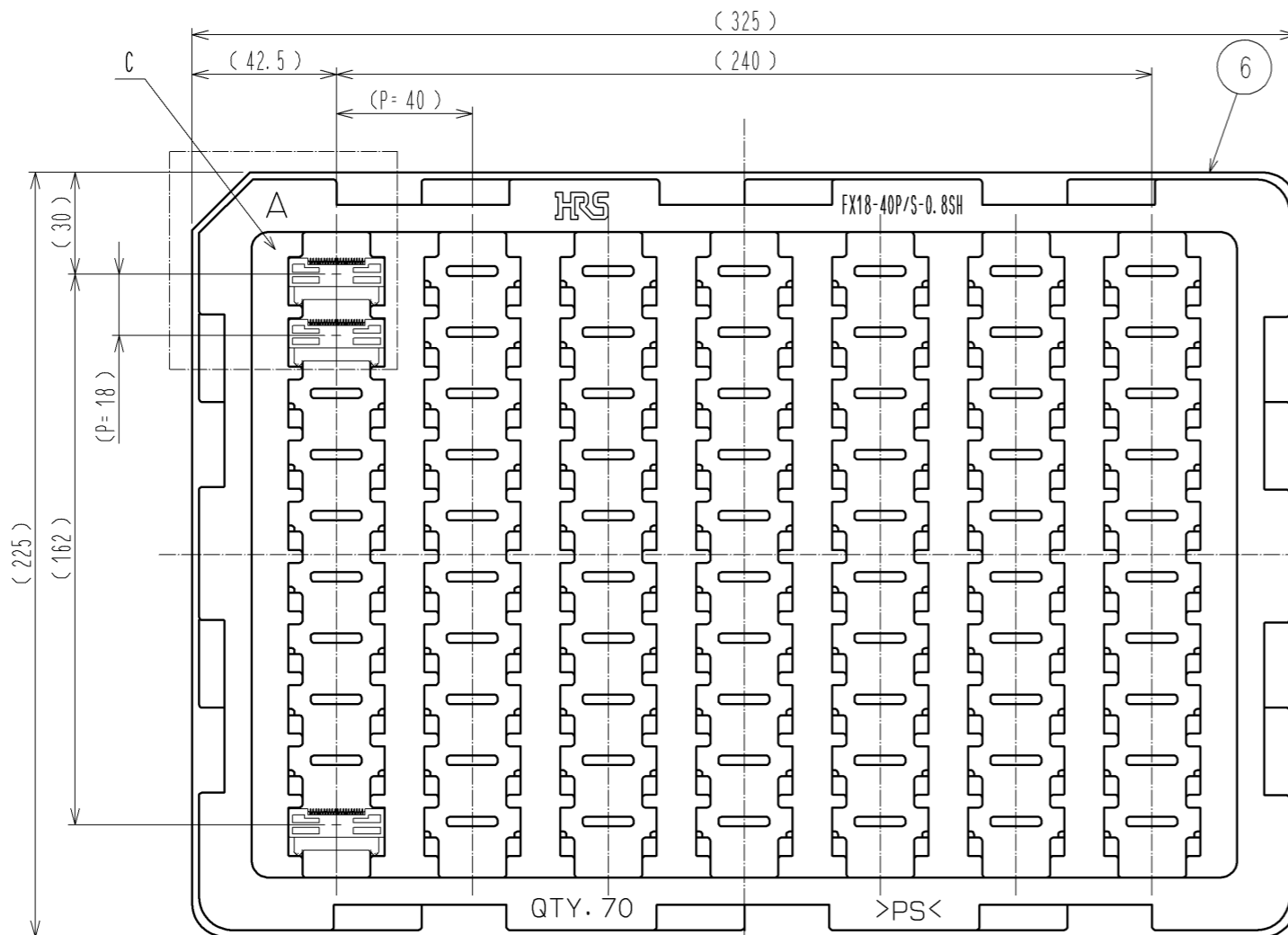
CONTACT AREA OF MF CONTACT A



SOLDERING POLE2 OF MF CONTACT A

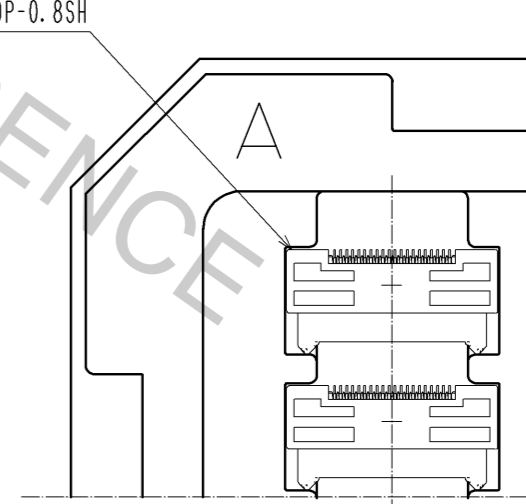
SOLDERING POLE1 OF MF CONTACT A

NOTE 8 SOLDERING LEAD OF MF CONTACT A SPLITS INTO TWO POLES.  
 BE SURE TO CONNECT TO THE SAME CIRCUIT.



C(1:1)

FX18-40P-0.8SH



DRAWING NO.	EDC3-159074-00
PART NO.	FX18-40P-0.8SH
CODE NO.	CL579-0002-5-00